

Electrostatic Discharged Protection Devices (ESD) Data Sheet

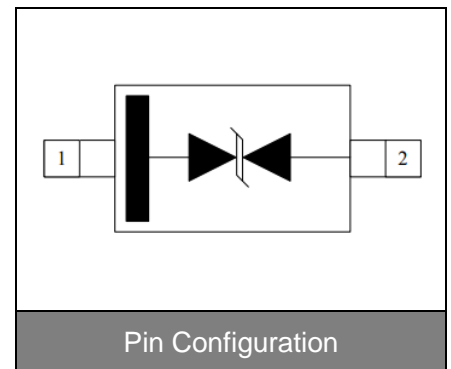
Description

The LAD92C5.0L01B of Transient Voltage Suppressors (TVS) is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computer, and PDAs. It offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. It is designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD), lightning, electrical fast transients (EFT), and cable discharge events (CDE).



Features

- IEC61000-4-2 ESD 25KV Air, 25KV contact compliance
- SOD923 surface mount package
- Peak power dissipation of 100W under 8/20µs waveform
- Working voltage: 5V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: 9C



Applications

- Portable Electronics
- Desktops, Servers and Notebooks
- Cellular Phones
- MP3 Ports
- Digital Camera Ports

Maximum Ratings

Rating	Symbol	Value	Unit
ESD voltage (Contact discharge)	V _{ESD}	±25	kV
ESD voltage (Air discharge)		±25	
Storage & operating temperature range	T _{STG} ,T _J	-55~+150	°C

Electrical Characteristics (T_J=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V _{RWM}				5	V
Reverse breakdown voltage	V _{BR}	I _{BR} =1mA	5.6		8	V
Reverse leakage current	I _R	V _R =5V			1	μA
Clamping voltage (tp=8/20μs)	V _C	I _{PP} =1A			9.8	V
Peak pulse current (tp=8/20μs)	I _{PP}				3	A
Off state junction capacitance	C _J	0Vdc,f=1MHz		17		pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

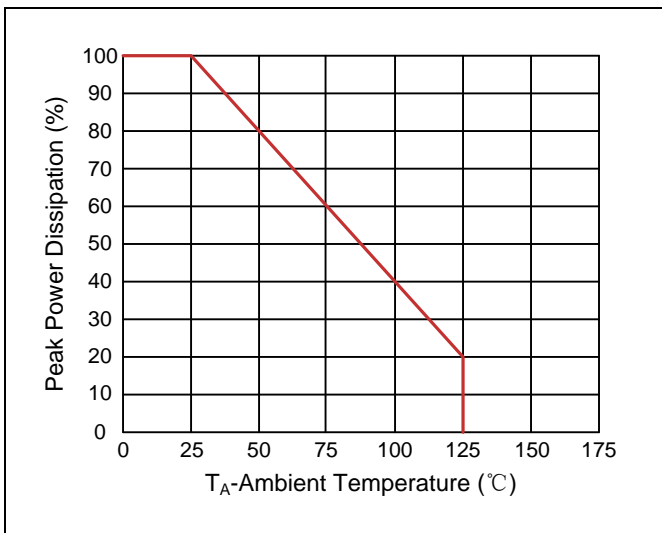


Figure 2. Pulse Waveforms

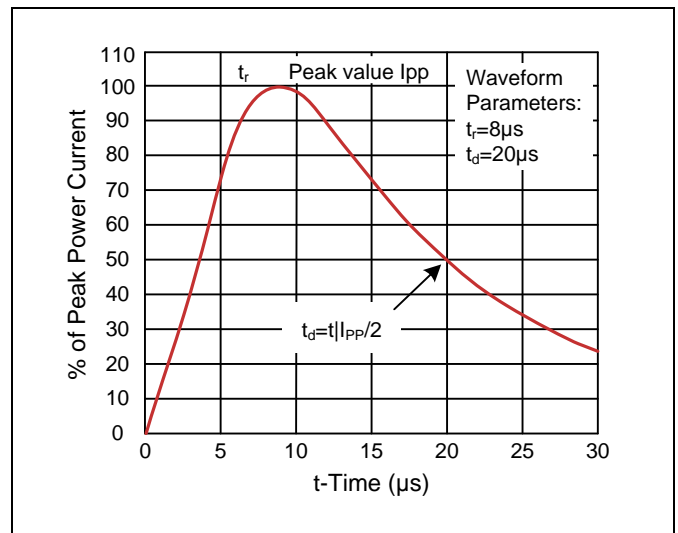


Figure 3. Clamping Voltage vs. Peak Pulse Current

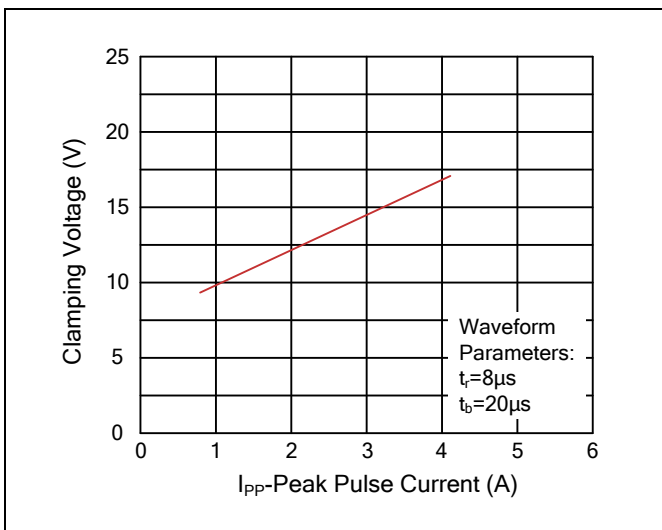
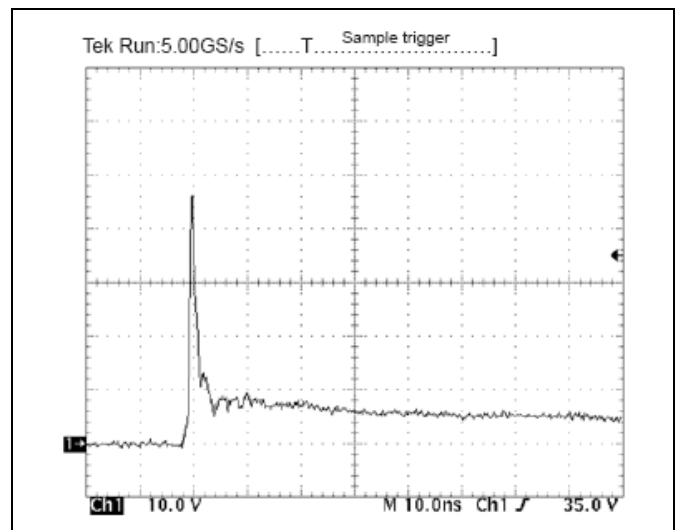
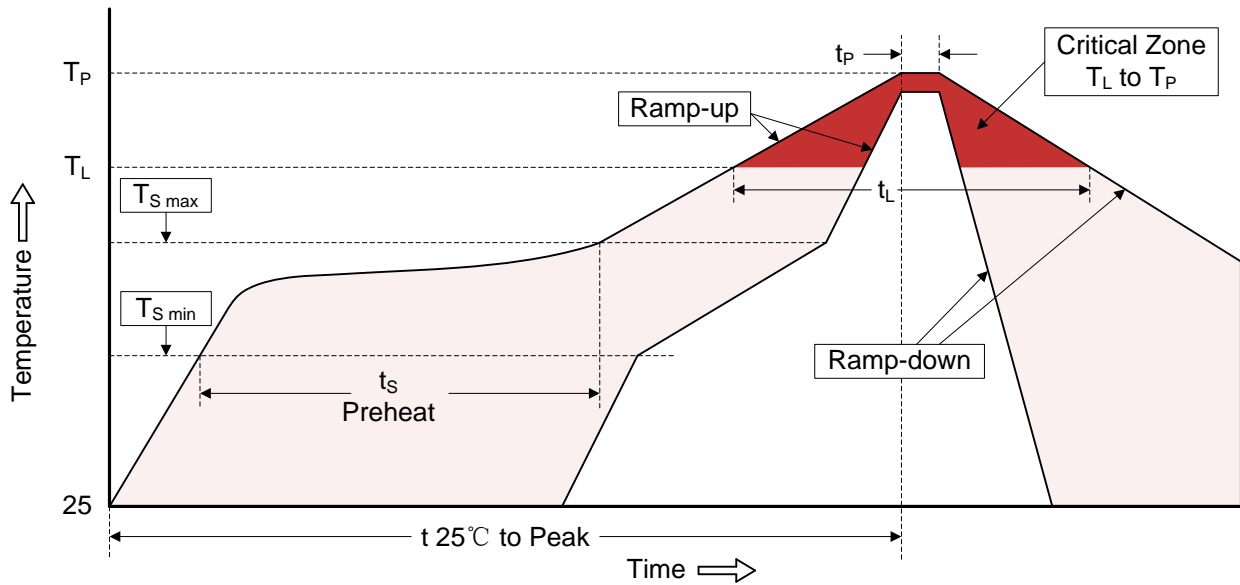


Figure 4. ESD Clamping(8kV Contact IEC61000-4-2)



Recommended Soldering Conditions

Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOD923)

Symbol	Dimension (mm)			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.36	0.43	0.014	0.017
B	0.07	0.17	0.003	0.007
C	0.55	0.65	0.022	0.026
D	0.15	0.25	0.006	0.010
E	0.75	0.85	0.030	0.033
F	0.95	1.05	0.037	0.041
G	0.05	0.15	0.002	0.006

Packaging

Tape	Symbol	Dimension (mm)
		W
	P0	4.00±0.10
	P1	2.00±0.10
	P2	2.00±0.10
	D0	Φ1.55±0.10
	D1	Φ0.50±0.05
	E	1.75±0.10
	F	3.50±0.10
	A	0.75±0.10
	B	1.20±0.10
	K	0.50±0.05
	t	0.20±0.05
Reel	D	Φ178.0±2.0
	D2	Φ13.0
	W1	9.5
		Quantity: 8000PCS